

# Microelectronic Adhesives

## DIE ATTACH ADHESIVES

Product #	Volume Resistivity (ohms-cm)	Thermal Conductivity (W/mK)	Application Technique	Comments
118-06 (PP)	0.0002	10	Pad-print	Ionically clean, microelectronic and die attach conductive adhesive.
118-06 (SP)	0.0002	10	Screen-print	Ionically clean, microelectronic and die attach conductive adhesive.
118-06 (SD)	0.0002	10	Syringe Dispense	Ionically clean, microelectronic and die attach conductive adhesive.
118-06 (ST)	0.0002	10	Stencil	Ionically clean, microelectronic and die attach conductive adhesive.
122-38 (SD)	0.0002	2.1	Syringe Dispense	Ionically clean, microelectronic and die attach conductive adhesive. Bonds to tin, lead and gold surfaces.
125-22	0.001	6.5	Screen-print	B-Stageable, low CTE conductive epoxy adhesive.
122-33 (SD)	1 X 10 <sup>16</sup>	1.25	Syringe Dispense	Thermally conductive, dielectric adhesive.
122-39 (SD)	1 X 10 <sup>16</sup>	5.5	Syringe Dispense	Thermally conductive, dielectric adhesive.

## SURFACE MOUNT ADHESIVES

Product #	Volume Resistivity (ohms-cm)	Thermal Conductivity (W/mK)	Application Technique	Comments
102-32	0.0001	12	Syringe Dispense	Silicone high temperature resistant. Flexible.
106-32A	0.0005	5.5	Syringe Dispense	High temperature resistant.
GPC-251 A/B	0.0002 - 0.005	6.74	Stencil	Silver filled, two part, room temperature curing epoxy adhesive. Designed for electrical and mechanical attachments of components and devices. Good for hand application.
118-15 A/B	0.0001 - 0.0004	6.5	Syringe Dispense	Easy 1 to 1 mix ratio. Low temperature curing. Long pot life.
124-08 A/B	0.0002 - 0.0004	6.5	Syringe Dispense	Excellent thermal shock resistance. Easy 1 to 1 mix ratio. Low temperature curing. Long pot life.
124-08LVC	0.0002 - 0.0004	6.5	Jet Dispense	Excellent thermal shock resistance. Easy 1 to 1 mix ratio. Low temperature curing. Long pot life.
119-05	0.00015	8.13	Syringe Dispense or Stencil	Can remain in liquid state up to 5 days without drying out. Single component.
118-06	0.0008	10	Pad-print	B-stageable, electrically conductive epoxy adhesive.

## FLIP CHIP ADHESIVES

Product #	Volume Resistivity (ohms-cm)	Comments
GPC-251 A/B	0.0002 - 0.005	Silver filled, two part, room temperature curing epoxy adhesive. Designed for electrical and mechanical attachments of components and devices. Good for hand application.
GPC-352-1 A/B-187	0.0005	Silver filled, two part, heat curing epoxy adhesive. Cures with excellent conductivity and is less sensitive to handling and ambient conditions. Typical applications are surface mount, component and heat sink attachment.
GPC-352-1 A/B119-44	0.0005	Same as above, except hardener B119-44 provides extended pot life.
121-20 A/B	1 X 10 <sup>12</sup> x, y axis 0.0001 z axis	Anisotropic, silver filled, two component, low temperature curing epoxy adhesive. Applications include conductive splicing of ribbon cables, bonding of flex circuits to PC boards, E.L. panels and touch screens and bonding of electrical components where short circuits caused by closely spaced contact pads are a concern.
121-23	1 X 10 <sup>12</sup> x, y axis 0.0001 z axis	Anisotropic, conductive, screen-printable, B-stageable epoxy adhesive suitable for application by screen-printing, dipping and syringe dispensing. Applications include bonding of flex circuits to PC boards and electrical attachment of surface mounted devices. Excellent adhesion to a variety of metallic contact pad compositions.

## FLIP CHIP UNDERFILL MATERIALS

Product #	Volume Resistivity (ohms-cm)	Comments
120-27 A/B-187	1 X 10 <sup>15</sup>	Black, low viscosity, two component, underfill epoxy potting and encapsulating compound. Formulated to rapidly release entrapped air during cure, providing a pin hole free surface.
113-33 A/B-187	1 X 10 <sup>15</sup>	Black, sag resistant glob top, flame-out, two component, epoxy potting and encapsulating compound. Material is crack resistant with a working life greater than four hours.
102-11 A/B-187	1 X 10 <sup>15</sup>	Black, crack resistant, flameout epoxy compound. Features long pot life and excellent resistance to thermal shock. Popular applications are encapsulating and bonding.
102-12 A/B-187	1 X 10 <sup>15</sup>	Black, thermal cycle resistant, epoxy compound with excellent resistance to thermal shock. Requires mild heat cure and has working life of greater than four hours.
116-04 A/B-187	1 X 10 <sup>15</sup>	Black, low viscosity, two component, underfill epoxy potting and encapsulating compound. Formulated for applications requiring excellent thermal conductivity.

PLEASE CONTACT US FOR OTHER MARKET SPECIFIC PRODUCT SELECTOR GUIDES



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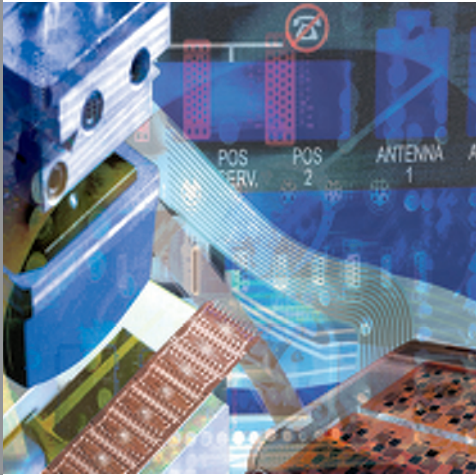
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